

## 600V Super-junction Power MOSFET

#### Description

#### 600V Super-junction Power MOSFET

Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs, designed according to the SJ principle. The deep trench SJ MOSFET provide an extremely low switching, communication and conduction losses device with highest robustness make especially resonant switching applications more reliable, more efficient, lighter and cooler, designed by Wuxi Unigroup Microelectronics Company.

Applications         • Very low FOM RDS(on)×Qg       • Switch Mode Power Supply (SMPS)         • 100% avalanche tested       • Switch Mode Power Supply (UPS)         • Easy to use/drive       • Power Factor Correction (PFC)         • RoHS compliant       • Charger         TO-220F       • Gate         • Gate       • Output         • Source       • Output         Device Marking and Package Information       • Output         Device Marking and Package       Marking         TPA60R160D       TO-220F       60R160D         Key Performance Parameter       • Value       Unit         Vos @ Tj.max       650       V         Rog(on),max       0.16       Ω         Q <sub>s/up</sub> 36       nC         Io_powlee       60       A					
• 100% avalanche tested • Luninterruptible Power Supply (UPS) • Power Factor Correction (PFC) • Charger TO-220F TO-220F Image: Source Drain Image: Source Oralise Image: Source Imag			Applications		
• Easy to use/drive • RoHS compliant • Power Factor Correction (PFC) • Charger TO-220F <b>Drain Gate Gate Gate Gate Constant Device Marking and Package Marking</b> TPA60R160D TO-220F <b>Bolice Package Marking Marking TPA60R160D</b> TO-220F <b>Bolice Package Marking Marking TPA60R160D TO-220F Bolice Constant Constant</b> <	<ul> <li>Very low FOM RDS(on)×Qg</li> </ul>				
• RoHS compliant         • Charger           TO-220F         Drain	• 100% avalanche tested		Uninterruptible Power Supply (UPS)		
DrainTO-220FDrain $Gate$ $Gate$ $Gate$ $Gate$ $Gate$ Device Marking and PackagePackageMarkingDevicePackageMarkingTPA60R160DTO-220F60R160DKey Performance ParameterValueUnitVos @ T_imax650V $Package$ 0.16 $\Omega$ $Q_{glyp}$ 36nCIp20A	-				
IO-220F       Image: Gate state	<ul> <li>RoHS compliant</li> </ul>		Charger		
SourceSourceDevice Marking and Package InformationDevicePackageMarkingTPA60R160DTO-220F60R160DKey Performance ParametersParameterValueUnitV_Ds @ T_I,max650VR_DS(on),max0.16ΩQ_g,typ36nCIp20A	TO-220F		Drain		
Device         Package         Marking           TPA60R160D         TO-220F         60R160D           Key Performance Parameters         Value         Unit           Parameter         Value         Value           V <sub>DS</sub> @T <sub>j,max</sub> 650         V           R <sub>DS(on),max</sub> 0.16         Ω           Q <sub>g,typ</sub> 36         nC           I <sub>D</sub> 20         A	111		Source RoHS		
TPA60R160D         TO-220F         60R160D           Key Performance Parameter         Value         Unit           Parameter         650         V           V <sub>DS</sub> @ T <sub>j,max</sub> 650         V           R <sub>DS(on),max</sub> 0.16         Ω           Q <sub>g,typ</sub> 36         nC           I <sub>D</sub> 20         A	Device Marking and Pa	ckage Information			
Key Performance Parameters         Value         Unit           Parameter         650         V           R <sub>DS(on),max</sub> 0.16         0           Q <sub>g,typ</sub> 36         nC           I <sub>D</sub> 20         A	Device	Package	Marking		
Parameter         Value         Unit           V <sub>DS</sub> @ T <sub>j,max</sub> 650         V           R <sub>DS(on),max</sub> 0.16         Ω           Q <sub>g,typ</sub> 36         nC           I <sub>D</sub> 20         A	TPA60R160D	TO-220F	60R160D		
V <sub>DS</sub> @ T <sub>j,max</sub> 650         V           R <sub>DS(on),max</sub> 0.16         Ω           Q <sub>g,typ</sub> 36         nC           I <sub>D</sub> 20         A	Key Performance Para	ameters			
Bis C μ, max         Definition         Definition         R           R <sub>DS(on),max</sub> 0.16         Ω           Q <sub>g,typ</sub> 36         nC           I <sub>D</sub> 20         A	Parameter	Value	Unit		
Q <sub>g,typ</sub> 36         nC           I <sub>D</sub> 20         A	V <sub>DS</sub> @ T <sub>j,max</sub>	650	V		
ID         20         A	R <sub>DS(on),max</sub>	0.16	Ω		
	Q <sub>g,typ</sub>	36	nC		
I <sub>D,pulse</sub> 60 A	I <sub>D</sub>	20	A		
	I <sub>D,pulse</sub>	60	A		
E <sub>OSS</sub> @ 400V 4.67 μJ	E <sub>oss</sub> @ 400V	4.67	μJ		



Absolute Maximum Ratings $T_c = 25^{\circ}C$ , unless otherwise noted					
Parameter		Symbol	Value	Unit	
Continuous Drain Current	T <sub>C</sub> = 25°C		20	A	
	T <sub>C</sub> = 100°C	I <sub>D</sub>	12		
Pulsed Drain Current (note1)		) I <sub>D,pulse</sub>	60	А	
Gate-Source Voltage		V <sub>GSS</sub>	±30	V	
Single Pulse Avalanche Energy (note2)		) E <sub>AS</sub>	450	mJ	
Avalanche Current		I <sub>AR</sub>	9.5	А	
MOSFET dv/dt Ruggedness, V <sub>DS</sub> = 0650V		dv/dt	50	V/ns	
Power Dissipation For TO-220F		P <sub>D</sub>	34	W	
Continuous Diode Forward Current		I <sub>S</sub>	20		
Diode Pulsed Current (note1)		) I <sub>S,pulse</sub>	60	A	
Reverse Diode dv/dt (note3)		3) dv/dt	5	A/us	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C	

Thermal Resistance For TO-220F				
Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	3.7	°C/W	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	80	-0/00	

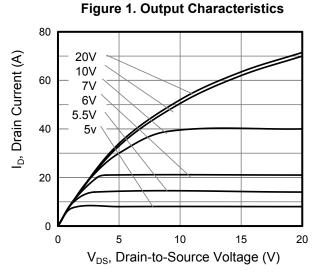


			Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics		•					
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_{D} = 250 \mu A$	600			V	
	1	$V_{DS}$ = 600V, $V_{GS}$ = 0V, $T_{J}$ = 25°C	-		1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 150°C			100		
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5		4.5	V	
Drain-Source On-State-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A		0.13	0.16	Ω	
Dynamic Characteristics					<u> </u>		
Input Capacitance	C <sub>iss</sub>	- V <sub>GS</sub> = 0V,		2216			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 50V,$		90		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		6			
Total Gate Charge	Qg			36			
Gate-Source Charge	Q <sub>gs</sub>	$V_{DD} = 520V, I_D = 20A, V_{GS} = 10V$		10		nC	
Gate-Drain Charge	$Q_gd$			12			
Turn-on Delay Time	t <sub>d(on)</sub>			45			
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> = 400V, I <sub>D</sub> = 20A,	-	68		20	
Turn-off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> = 25Ω		130		ns	
Turn-off Fall Time	t <sub>f</sub>		-	9			
Drain-Source Body Diode Characte	ristics						
Body Diode Forward Voltage	$V_{SD}$	$T_J$ = 25°C, $I_{SD}$ = 20A, $V_{GS}$ = 0V		0.95	1.2	V	
Reverse Recovery Time	t <sub>rr</sub>			450		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	V <sub>R</sub> = 400V, I <sub>S</sub> =3A, di <sub>⊧</sub> /dt = 100A/µs		8.1		μC	
Peak Reverse Recovery Current	I <sub>rrm</sub>			3.4		А	

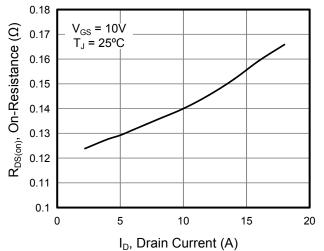
#### Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2.  $V_{DD}$  = 50V,  $R_G$  = 25 $\Omega$ , Starting  $T_J$  = 25°C
- 3. Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  1%

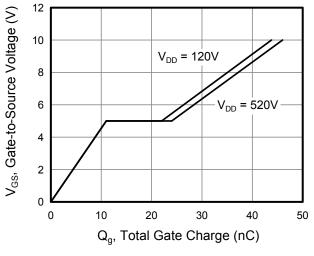
#### **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

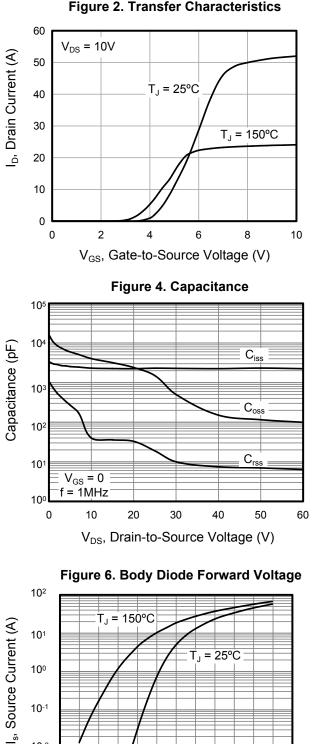












0.8

V<sub>SD</sub>, Source-to-Drain Voltage (V)

0.6

1

#### Figure 2. Transfer Characteristics

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1.2

1.4

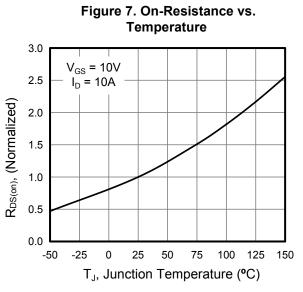
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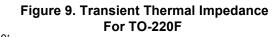
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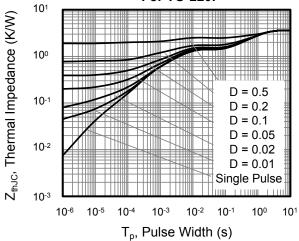
0.2

0.4

# E









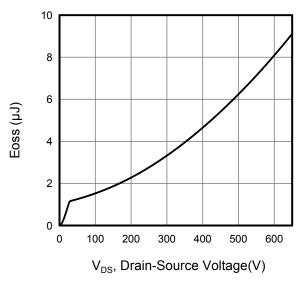


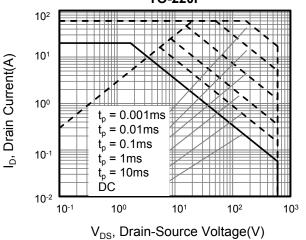
Figure 8. Breakdown voltage vs. **Junction Temperature** 1.3  $I_{D} = 250 \mu A$ 1.2 1.1 1 0.9 0.8 -30 0 30 60 90 120 150

V<sub>BR(DSS)</sub>, (Normalized)

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Figure 10. Safe Operation Area For TO-220F

T<sub>J</sub>, Junction Temperature (°C)



V1.0



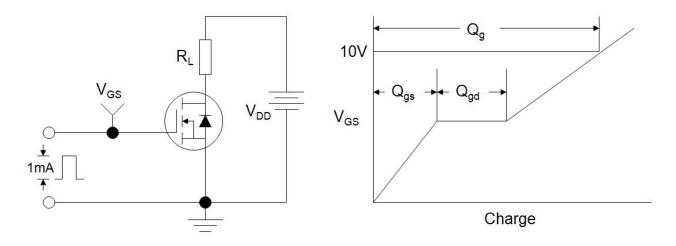


Figure B: Resistive Switching Test Circuit and Waveform

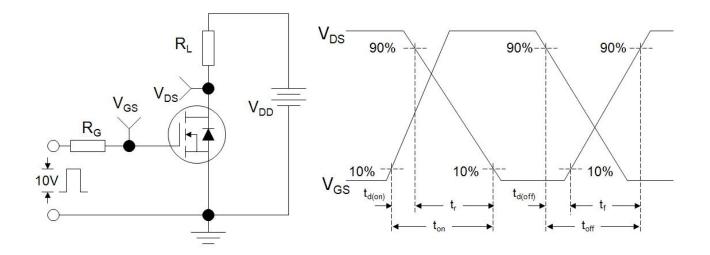
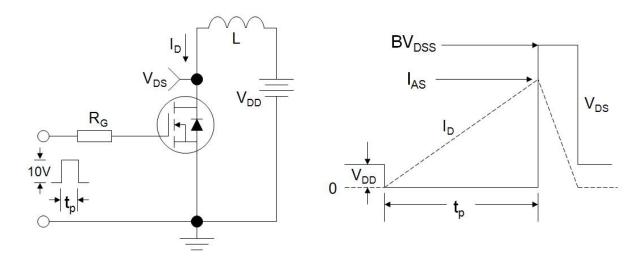
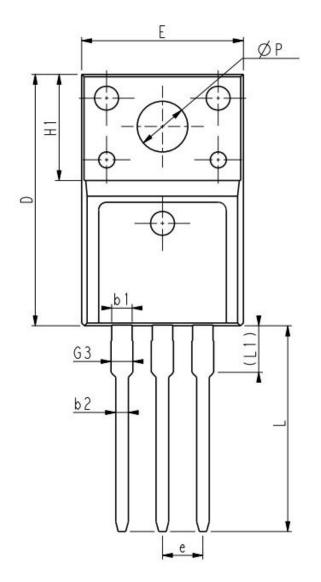


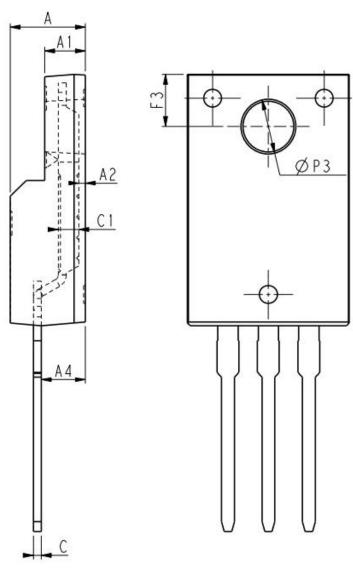
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



TO-220F(封装厂 H)



It



	Unit:mm				
Symb	Max.	Nom	Min.	Symbol	
e	10.36	10.16	9.96	E	
L	4.90	4.70	4.50	А	
L1	2.74	2.54	2.34	A1	
ΦP	0.60	0.45	0.30	A2	
ΦΡ	2.96	2.76	2.56	A4	
F3	0.65	0.50	0.40	С	
G3	1.35	1.30	1.20	c1	
b1	16.17	15.87	15.57	D	
b2	6.70REF			H1	

Unit:mm					
Symbol	Min.	Nom	Max.		
е		2.54BSC			
L	12.68	12.98	13.28		
L1	2.93	3.03	3.13		
ΦP	3.03	3.18	3.38		
ΦΡ3	3.15	3.45	3.65		
F3	3.15	3.30	3.45		
G3	1.25	1.35	1.55		
b1	1.18	1.28	1.43		
b2	0.70	0.80	0.95		



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